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Atty. Docket No. CPAC 1017-6
Appl. No. 10/632,553

APR 8 2005

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnczos)

Application No.: 10/632,553)

Filed: August 2, 2003)

Title: **Semiconductor multi-package module having)
package stacked over die-down flip chip ball)
grid array package and having a wire bond)
interconnect between stacked packages)**

Examiner: Dao H. Nguyen

Group Art Unit: 2818

Date: 8 April 2005.

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office, at the Central Fax No. 703 872-9306 on April 8, 2005.

Signed


Paula Furlk Hurley

RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

Responsive to the Office action mailed March 22, 2005 (Restriction only), Applicants elect:

Group I, claims 1 - 19 and 39 - 40.

Amendments to the Specification begin on page 2 of this paper.

There are no amendments to the claims. A **Listing of Claims** is included for the Examiner's convenience, beginning on page 3 of this paper.

Remarks begin on page 8 of this paper.